

100350 Low Power Hex D-Latch

General Description

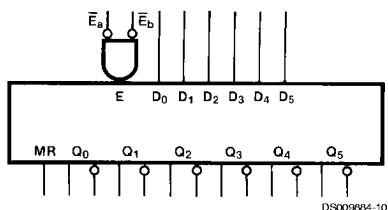
The 100350 contains six D-type latches with true and complement outputs, a pair of common Enables ($\bar{E}_a$ and $\bar{E}_b$), and a common Master Reset (MR). A Q output follows its D input when both $\bar{E}_a$ and $\bar{E}_b$ are LOW. When either $\bar{E}_a$ or $\bar{E}_b$ (or both) are HIGH, a latch stores the last valid data present on its D input before $\bar{E}_a$ or $\bar{E}_b$ went HIGH. The MR input overrides all other inputs and makes the Q outputs LOW. All inputs have 50 k Ω pull-down resistors.

Features

- 20% power reduction of the 100150
- 2000V ESD protection
- Pin/function compatible with 100150
- Voltage compensated operating range = -4.2V to -5.7V

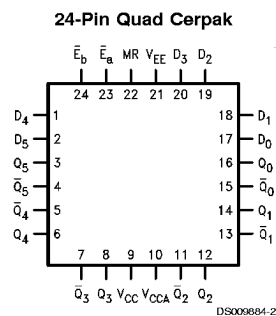
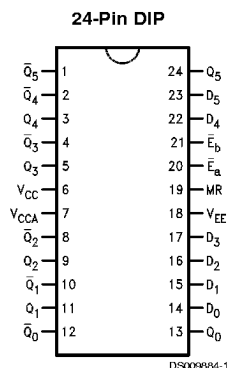
Ordering Code:

Logic Symbol

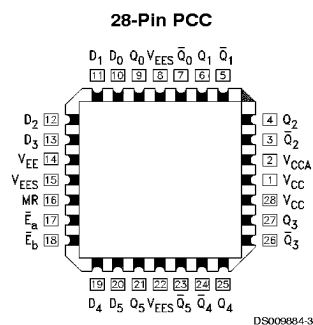


Pin Names	Description
D ₀ –D ₅	Data Inputs
$\bar{E}_a$, $\bar{E}_b$	Common Enable Inputs (Active LOW)
MR	Asynchronous Master Reset Input
Q ₀ –Q ₅	Data Outputs
$\bar{Q}_0$ – $\bar{Q}_5$	Complementary Data Outputs

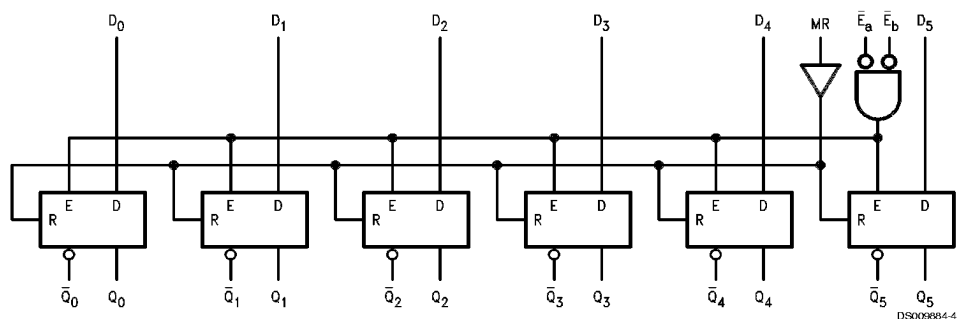
Connection Diagrams



Connection Diagrams (Continued)



Logic Diagram



Truth Tables (Each Latch)

Inputs				Outputs
D_n	$\bar{E}_a$	$\bar{E}_b$	MR	Q_n
L	L	L	L	L
H	L	L	L	H
X	H	X	L	Latched (Note 1)
X	X	H	L	Latched (Note 1)

H = HIGH Voltage Level

H = HIGH Voltage Level
L = LOW Voltage Level

X = Don't Care

Note 1: Retains data present before $\bar{E}$ positive transition

Asynchronous Operation

Inputs				Outputs
D_n	$\overline{E}_a$	$\overline{E}_b$	MR	Q_n
X	X	X	H	L

Absolute Maximum Ratings (Note 2)

Storage Temperature (T_{STG})	–65°C to +150°C
Maximum Junction Temperature (T_J)	
Ceramic	+175°C
Plastic	+150°C
V_{EE} Pin Potential to Ground Pin	–7.0V to +0.5V
Input Voltage (DC)	V_{EE} to +0.5V
Output Current (DC Output HIGH)	–50 mA
ESD (Note 3)	≥2000V

Recommended Operating Conditions

Case Temperature (T_C)	
Commercial	0°C to +85°C
Military	–55°C to +125°C
Supply Voltage (V_{EE})	–5.7V to –4.2V

Note 2: Absolute maximum ratings are those values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 3: ESD testing conforms to MIL-STD-883, Method 3015.

Commercial Version**DC Electrical Characteristics** (Note 4)

$V_{EE} = -4.5V$ to $-5.7V$, $V_{CC} = V_{CCA} = GND$, $T_C = 0^\circ C$ to $+85^\circ C$

Symbol	Parameter	Min	Typ	Max	Units	Conditions	
V _{OH}	Output HIGH Voltage	–1025	–955	–870	mV	V _{IN} = V _{IH (Max)} or V _{IL (Min)}	Loading with 50Ω to –2.0V
V _{OL}	Output LOW Voltage	–1830	–1705	–1620			
V _{OHC}	Output HIGH Voltage	–1035			mV	V _{IN} = V _{IH (Min)} or V _{IL (Max)}	Loading with 50Ω to –2.0V
V _{OLC}	Output LOW Voltage			–1610			
V _{IH}	Input HIGH Voltage	–1165		–870	mV	Guaranteed HIGH Signal for All Inputs	
V _{IL}	Input LOW Voltage	–1830		–1475	mV	Guaranteed LOW Signal for All Inputs	
I _{IL}	Input LOW Current	0.50			μA	V _{IN} = V _{IL (Min)}	
I _{IH}	Input HIGH Current MR D _n E _a , E _b			240	μA	V _{IN} = V _{IH (Max)}	
				240			
				240			
				240			
I _{EE}	Power Supply Current	–89 –93		–44 –44	mA	Inputs Open V _{EE} = –4.2V to –4.8V V _{EE} = –4.2V to –5.7V	

Note 4: The specified limits represent the “worst case” value for the parameter. Since these values normally occur at the temperature extremes, additional noise immunity and guard banding can be achieved by decreasing the allowable system operating ranges. Conditions for testing shown in the tables are chosen to guarantee operation under “worst case” conditions.

DIP AC Electrical Characteristics

$V_{EE} = -4.2V$ to $-5.7V$, $V_{CC} = V_{CCA} = GND$

Symbol	Parameter	$T_C = 0^\circ C$		$T_C = +25^\circ C$		$T_C = +85^\circ C$		Units	Conditions
		Min	Max	Min	Max	Min	Max		
t_{PLH}	Propagation Delay							ns	Figures 1, 2
t_{PHL}	D_n to Output (Transparent Mode)	0.50	1.40	0.50	1.40	0.50	1.50		
t_{PLH}	Propagation Delay	0.75	1.85	0.75	1.85	0.75	2.05	ns	Figures 1, 3
t_{PHL}	$\bar{E}_a, \bar{E}_b$ to Output								
t_{PLH}	Propagation Delay	0.90	2.10	0.90	2.10	0.90	2.10	ns	Figures 1, 2
t_{PHL}	MR to Output								
t_{TLH}	Transition Time	0.35	1.30	0.35	1.30	0.35	1.30	ns	Figures 3, 4
t_{THL}	20% to 80%, 80% to 20%								
t_s	Setup Time							ns	Figure 4
	D_0 – D_5	1.00		1.00		1.00			
	MR (Release Time)	1.60		1.60		1.60			
t_h	Hold Time, D_0 – D_5	0.40		0.40		0.40		ns	

DIP AC Electrical Characteristics (Continued)

$V_{EE} = -4.2V$ to $-5.7V$, $V_{CC} = V_{CCA} = GND$

Symbol	Parameter	$T_C = 0^\circ C$		$T_C = +25^\circ C$		$T_C = +85^\circ C$		Units	Conditions
		Min	Max	Min	Max	Min	Max		
$t_{pw(L)}$	Pulse Width LOW $\bar{E}_a, \bar{E}_b$	2.00		2.00		2.00		ns	Figure 2
$t_{pw(H)}$	Pulse Width HIGH, MR	2.00		2.00		2.00		ns	Figure 3

PCC and Cerpak AC Electrical Characteristics

$V_{EE} = -4.2V$ to $-5.7V$, $V_{CC} = V_{CCA} = GND$

Symbol	Parameter	$T_C = 0^\circ C$		$T_C = +25^\circ C$		$T_C = +85^\circ C$		Units	Conditions
		Min	Max	Min	Max	Min	Max		
t_{PLH} t_{PHL}	Propagation Delay D_n to Output (Transparent Mode)	0.50	1.20	0.50	1.20	0.50	1.30	ns	Figures 1, 2
t_{PLH} t_{PHL}	Propagation Delay $\bar{E}_a, \bar{E}_b$ to Output	0.75	1.65	0.75	1.65	0.75	1.85	ns	
t_{PLH} t_{PHL}	Propagation Delay MR to Output	0.90	1.90	0.90	1.90	0.90	1.90	ns	Figures 1, 3
t_{TLH} t_{THL}	Transition Time 20% to 80%, 80% to 20%	0.35	1.10	0.35	1.10	0.35	1.10	ns	Figures 1, 2
t_s	Setup Time D_0-D_5 MR (Release Time)	0.90 1.50		0.90 1.50		0.90 1.50		ns	Figures 3, 4
t_h	Hold Time, D_0-D_5	0.30		0.30		0.30		ns	Figure 4
$t_{pw(L)}$	Pulse Width LOW $\bar{E}_a, \bar{E}_b$	2.00		2.00		2.00		ns	Figure 2
$t_{pw(H)}$	Pulse Width HIGH, MR	2.00		2.00		2.00		ns	Figure 3

Military Version—Preliminary

DC Electrical Characteristics

$V_{EE} = -4.2V$ to $-5.7V$, $V_{CC} = V_{CCA} = GND$, $T_C = -55^\circ C$ to $+125^\circ C$

Symbol	Parameter	Min	Max	Units	T _C	Conditions		Notes
V _{OH}	Output HIGH Voltage	-1025 -1085	-870	mV	0°C to +125°C -55°C	V _{IN} = V _{IH} (Max) or V _{IL} (Min)	Loading with 50Ω to -2.0V	(Notes 5, 6, 7)
V _{OL}	Output LOW Voltage	-1830 -1830	-1620 -1555	mV	0°C to +125°C -55°C			
V _{OHc}	Output HIGH Voltage	-1035 -1085		mV	0°C to +125°C -55°C	V _{IN} = V _{IH} (Min) or V _{IL} (Min)	Loading with 50Ω to -2.0V	(Notes 5, 6, 7)
V _{OLc}	Output LOW Voltage		-1610 -1555	mV	0°C to +125°C -55°C			
V _{IH}	Input HIGH Voltage	-1165	-870	mV	-55°C to +125°C	Guaranteed HIGH Signal for All Inputs		(Notes 5, 6, 7, 8)
V _{IL}	Input LOW Voltage	-1830	-1475	mV	-55°C to +125°C	Guaranteed LOW Signal for All Inputs		(Notes 5, 6, 7, 8)
I _{IL}	Input LOW Current	0.50		μA	-55°C to +125°C	V _{EE} = -4.2V V _{IN} = V _{IL} (Min)		(Notes 5, 6, 7)

DC Electrical Characteristics (Continued)

$V_{EE} = -4.2V$ to $-5.7V$, $V_{CC} = V_{CCA} = GND$, $T_C = -55^{\circ}C$ to $+125^{\circ}C$

Symbol	Parameter	Min	Max	Units	T_C	Conditions	Notes
I_{IH}	Input HIGH Current						(Notes 5, 6, 7)
	MR		300				
	D_n		250	μA	$0^{\circ}C$ to $+125^{\circ}C$	$V_{EE} = -5.7V$	
	$\bar{E}_a, \bar{E}_b$		520			$V_{IN} = V_{IH} (Max)$	
	MR		450				
	D_n		350	μA	$-55^{\circ}C$		
	$\bar{E}_a, \bar{E}_b$		750				
I_{EE}	Power Supply Current	-138	-64	mA	$-55^{\circ}C$ to $+125^{\circ}C$	Inputs Open	(Notes 5, 6, 7)

Note 5: F100K 300 Series cold temperature testing is performed by temperature soaking (to guarantee junction temperature equals $-55^{\circ}C$), then testing immediately without allowing for the junction temperature to stabilize due to heat dissipation after power-up. This provides "cold start" specs which can be considered a worst case condition at cold temperatures.

Note 6: Screen tested 100% on each device at $-55^{\circ}C$, $+25^{\circ}C$, and $+125^{\circ}C$, Subgroups 1, 2, 3, 7, and 8.

Note 7: Sample tested (Method 5005, Table I) on each manufactured lot at $-55^{\circ}C$, $+25^{\circ}C$, and $+125^{\circ}C$, Subgroups A1, 2, 3, 7, and 8.

Note 8: Guaranteed by applying specified input condition and testing V_{OH}/V_{OL} .

AC Electrical Characteristics

$V_{EE} = -4.2V$ to $-5.7V$, $V_{CC} = V_{CCA} = GND$

Symbol	Parameter	$T_C = -55^{\circ}C$		$T_C = +25^{\circ}C$		$T_C = +125^{\circ}C$		Units	Conditions	Notes
		Min	Max	Min	Max	Min	Max			
t_{PLH}	Propagation Delay									(Notes 9, 10, 11)
t_{PHL}	D_n to Output (Transparent Mode)	0.45	1.50	0.50	1.40	0.50	1.50	ns	Figures 1, 2	
t_{PLH}	Propagation Delay									
t_{PHL}	$\bar{E}_a, \bar{E}_b$ to Output	0.75	2.05	0.75	1.85	0.75	2.05	ns		
t_{PLH}	Propagation Delay									
t_{PHL}	MR to Output	0.80	2.40	0.90	2.40	0.90	2.60	ns	Figures 1, 3	
t_{TLH}	Transition Time	0.45	1.70	0.45	1.60	0.45	1.60	ns	Figures 1, 2	(Note 12)
t_{THL}	20% to 80%, 80% to 20%									
t_S	Setup Time									
	D_0 - D_5	0.70		0.70		0.70		ns	Figures 1, 2	
	MR (Release Time)	2.10		2.10		2.10				
t_H	Hold Time, D_0 - D_5	0.70		0.70		0.70		ns	Figure 4	
$t_{pw}(L)$	Pulse Width LOW	2.00		2.00		2.00		ns	Figure 2	
	$\bar{E}_a, \bar{E}_b$									
$t_{pw}(L)$	Pulse Width HIGH, MR	2.00		2.00		2.00		ns	Figure 3	

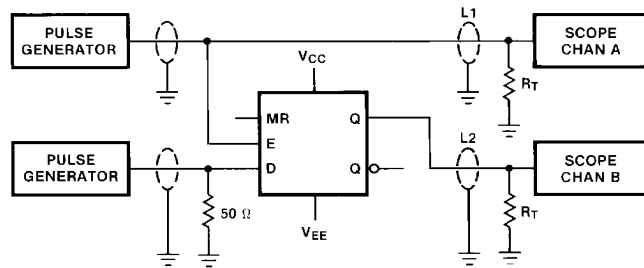
Note 9: F100K 300 Series cold temperature testing is performed by temperature soaking (to guarantee junction temperature equals $-55^{\circ}C$), then testing immediately without allowing for the junction temperature to stabilize due to heat dissipation after power-up. This provides "cold start" specs which can be considered a worst case condition at cold temperatures.

Note 10: Screen tested 100% on each device at $+25^{\circ}C$, temperature only, Subgroup A9.

Note 11: Sample tested (Method 5005, Table I) on each Mfg. lot at $+25^{\circ}C$, Subgroup A9, and at $+125^{\circ}C$, and $-55^{\circ}C$ temp., Subgroups A10 and A11.

Note 12: Not tested at $+25^{\circ}C$, $+125^{\circ}C$, and $-55^{\circ}C$ temperature (design characterization data).

Test Circuit



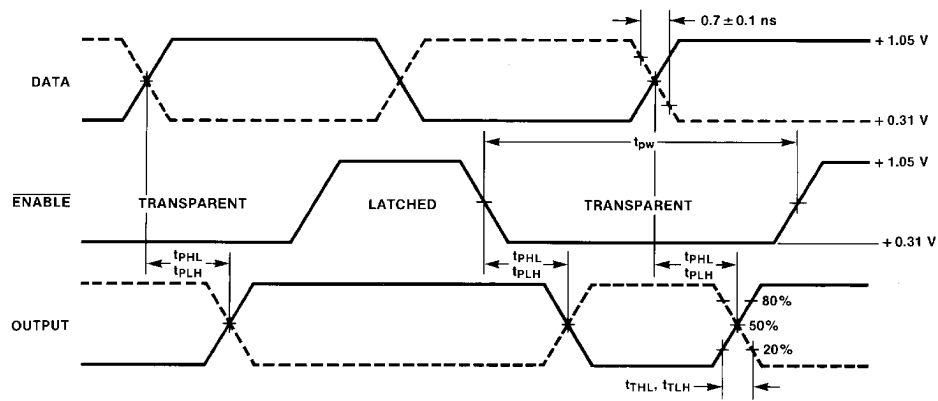
DS009884-5

Notes:

$V_{CC}, V_{CCA} = +2V, V_{EE} = -2.5V$
 $L1$ and $L2$ = equal length 50Ω impedance lines
 $R_T = 50\Omega$ terminator internal to scope
 Decoupling $0.1 \mu F$ from GND to V_{CC} and V_{EE}
 All unused outputs are loaded with 50Ω to GND
 C_L = Fixture and stray capacitance $\leq 3 pF$

FIGURE 1. AC Test Circuit

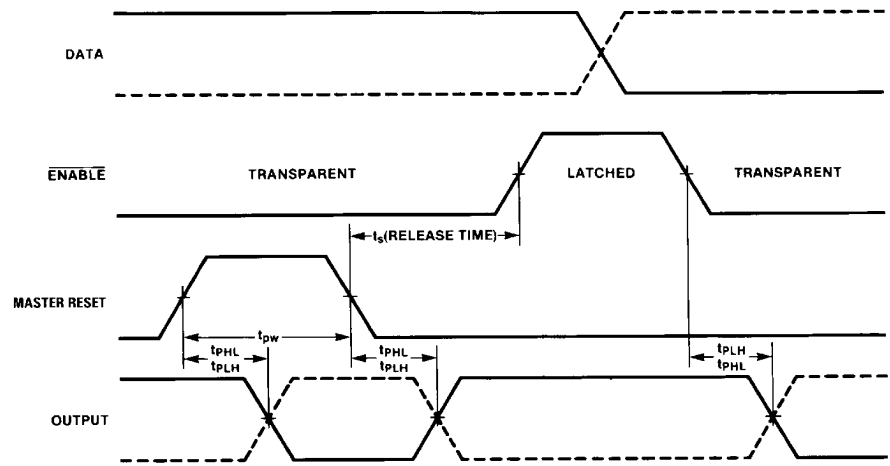
Switching Waveforms



DS009884-6

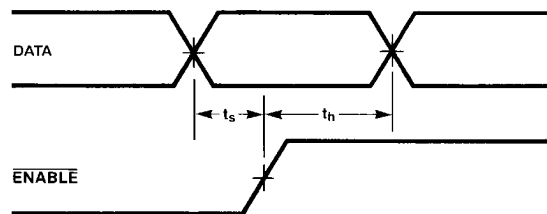
FIGURE 2. Enable Timing

Switching Waveforms (Continued)



DS000884-7

FIGURE 3. Reset Timing

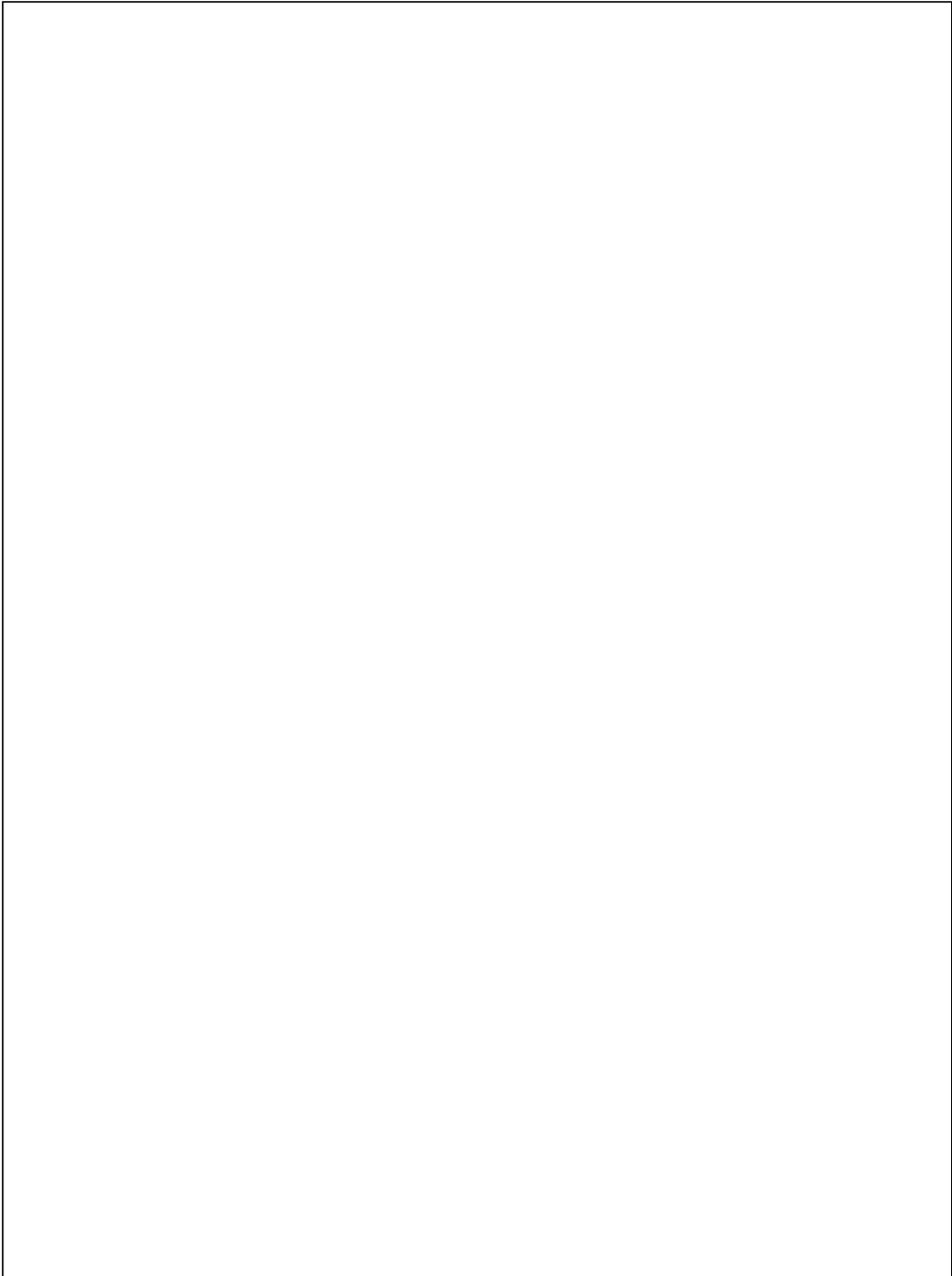


DS000884-8

Notes:

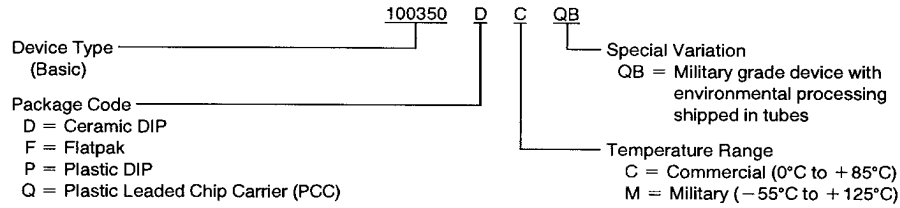
t_s is the minimum time before the transition of the enable that information must be present at the data input.
 t_h is the minimum time after the transition of the enable that information must remain unchanged at the data input.

FIGURE 4. Data Setup and Hold Time



Ordering Information

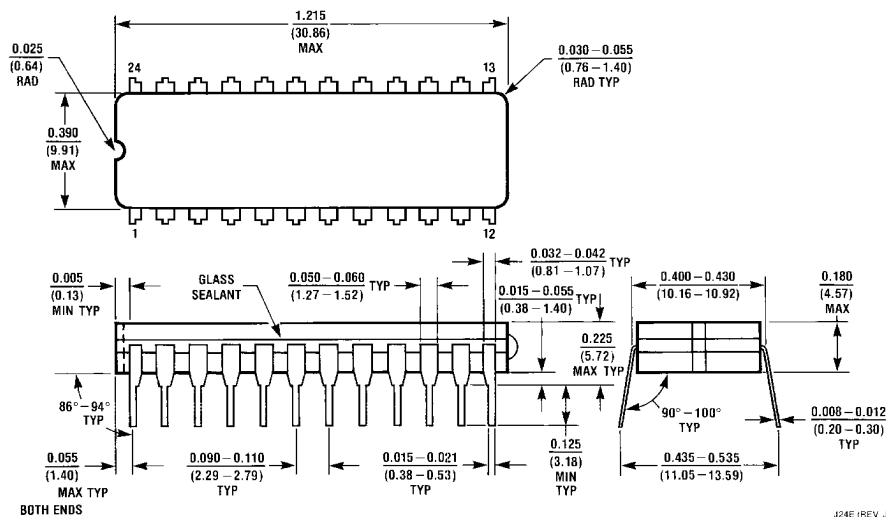
The device number is used to form part of a simplified purchasing code where a package type and temperature range are defined as follows:



DS009804-11

Physical Dimensions

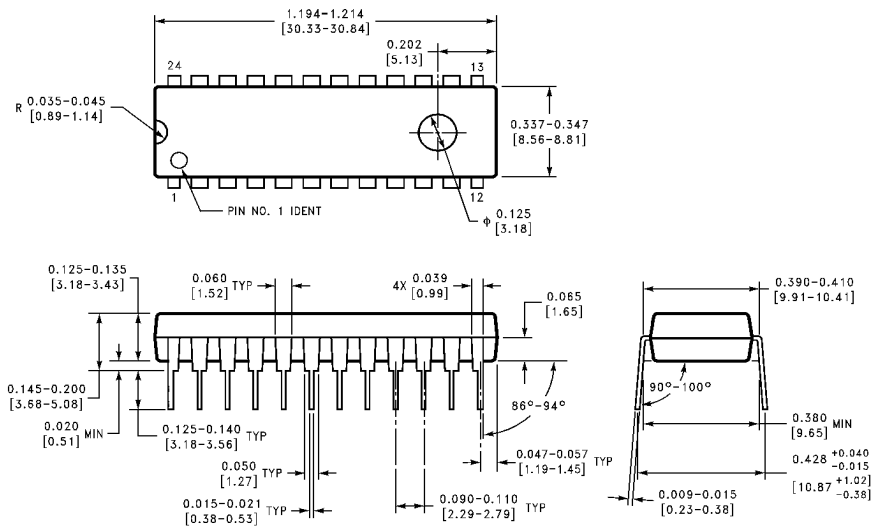
inches (millimeters) unless otherwise noted



J24E (REV. J)

24-Lead Ceramic Dual-In-Line Package (0.400" Wide) (D)
Package Number J24E

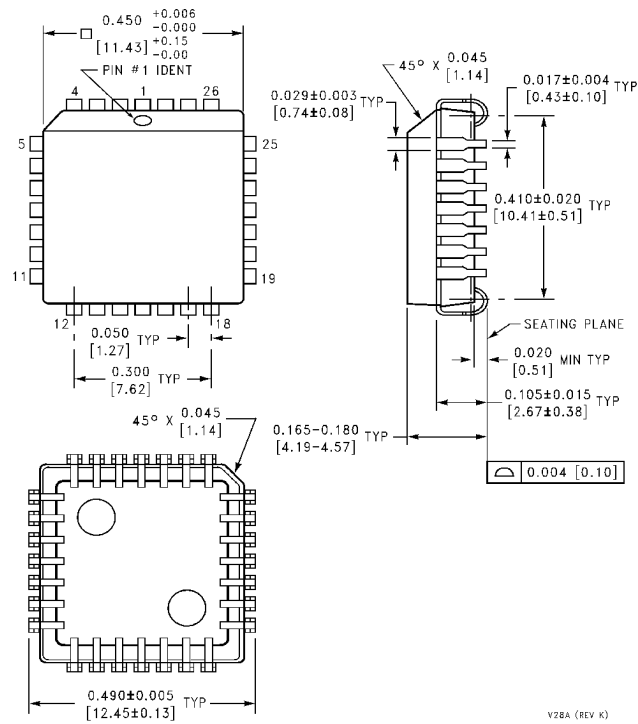
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



24-Lead Plastic Dual-In-Line Package (P)
Package Number N24E

N24E (REV A)

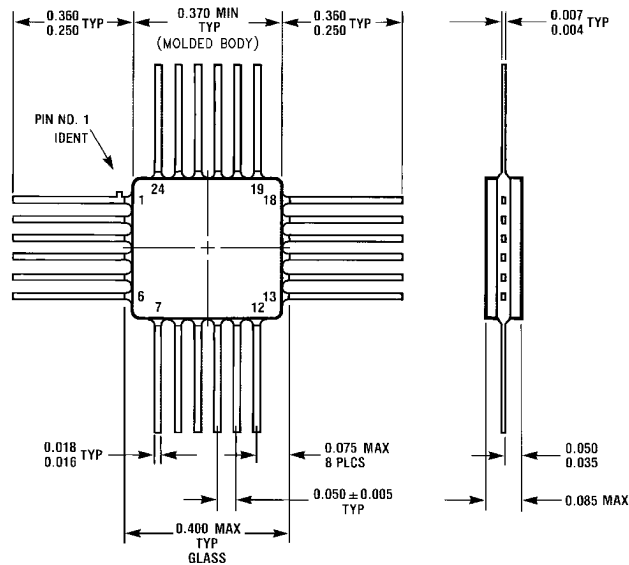
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



28-Lead Plastic Chip Carrier (Q)
Package Number V28A

V28A (REV K)

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



W24B (REV D)

24-Lead Quad Cerpak (F)
Package Number W24B

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